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Details

Product Status	Obsolete
Core Processor	-
Core Size	-
Speed	-
Connectivity	-
Peripherals	-
Number of I/O	-
Program Memory Size	-
Program Memory Type	-
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	-
Data Converters	-
Oscillator Type	-
Operating Temperature	-
Mounting Type	-
Package / Case	-
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m301n2f8vfp-u3

1.2 Performance Overview

Table 1.1 gives an overview of the M16C/1N group performance specification.

Table 1.1 Performance overview

Item		Performance
Number of basic instructions		91 instructions
Shortest instruction execution time		62.5 ns (when $f(X_{IN})=16\text{MHz}$)
Memory size	ROM	See Table 1.2 Performance overview
	RAM	See Table 1.2 Performance overview
I/O port		P0 to P5: 37 lines
Multifunction timer	T1	8 bits x 1
	TX, TY, TZ	8 bits x 3
	TC	16 bits x 1
Serial I/O (UART or clock synchronous)		x 2
A/D converter (maximum resolution: 10 bits)		x 12 channels (Expandable up to 14 channels)
D/A converter		8 bits x 1
CAN controller		1 channel, 2.0B active
Watchdog timer		15 bits x 1 (with prescaler)
Interrupts		15 internal causes, 8 external causes, 4 software causes
Clock generating circuits		3 internal circuits
Power supply voltage		4.2 V to 5.5V (when $f(X_{IN})=16\text{MHz}$)
Power consumption		70mW($V_{CC}=5.0\text{V}$, $f(X_{IN})=16\text{MHz}$)
I/O characteristics	I/O withstand voltage	5V
	Output current	5mA (10mA:LED drive port)
Device configuration		CMOS silicon gate
Package		48-pin LQFP

1.5 Pin Configuration

Figure 1.3 shows pin configurations (top view) of the M16C/1N group.

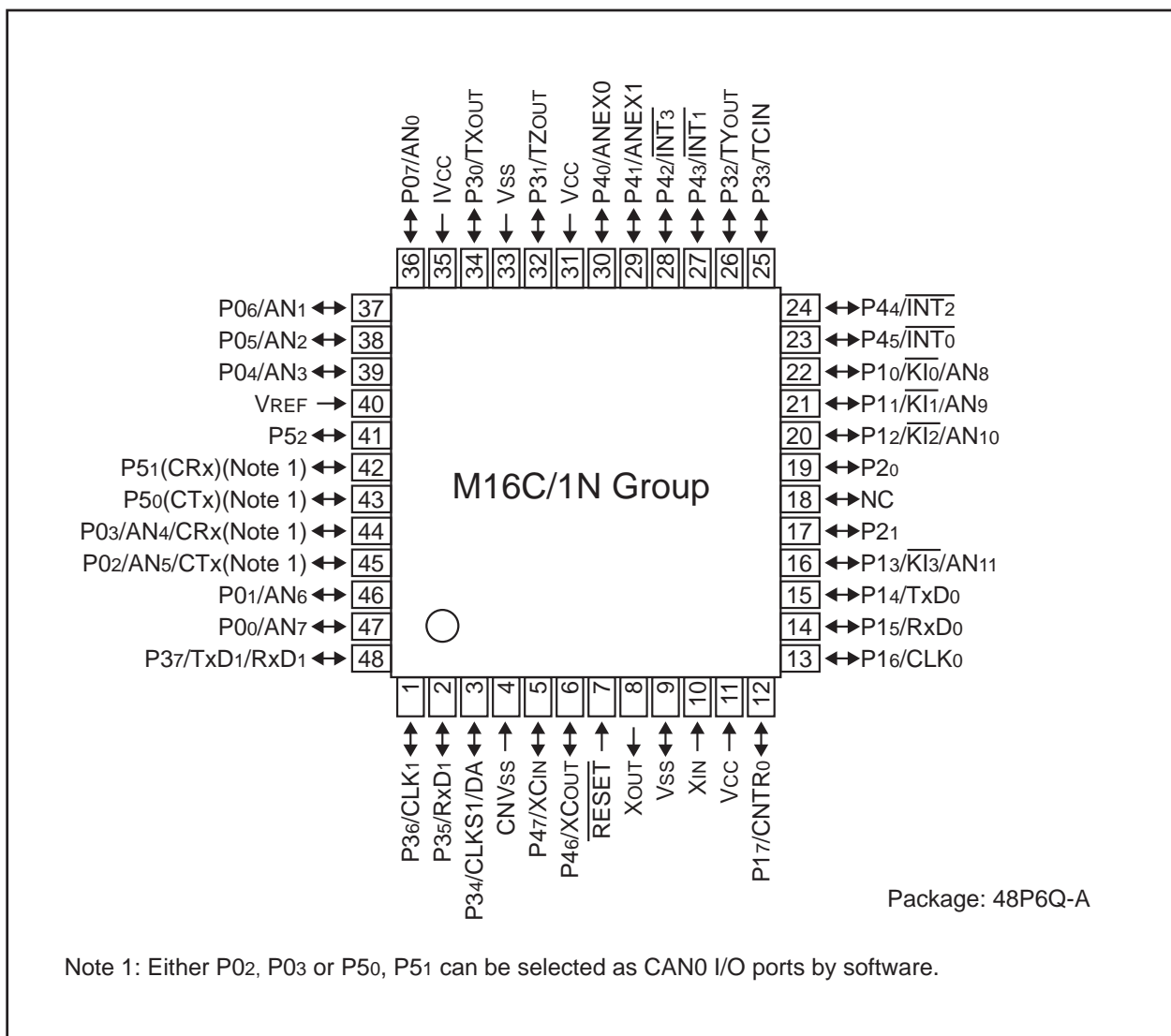


Figure 1.3 Pin configuration diagram (top view)

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. There are two register banks.

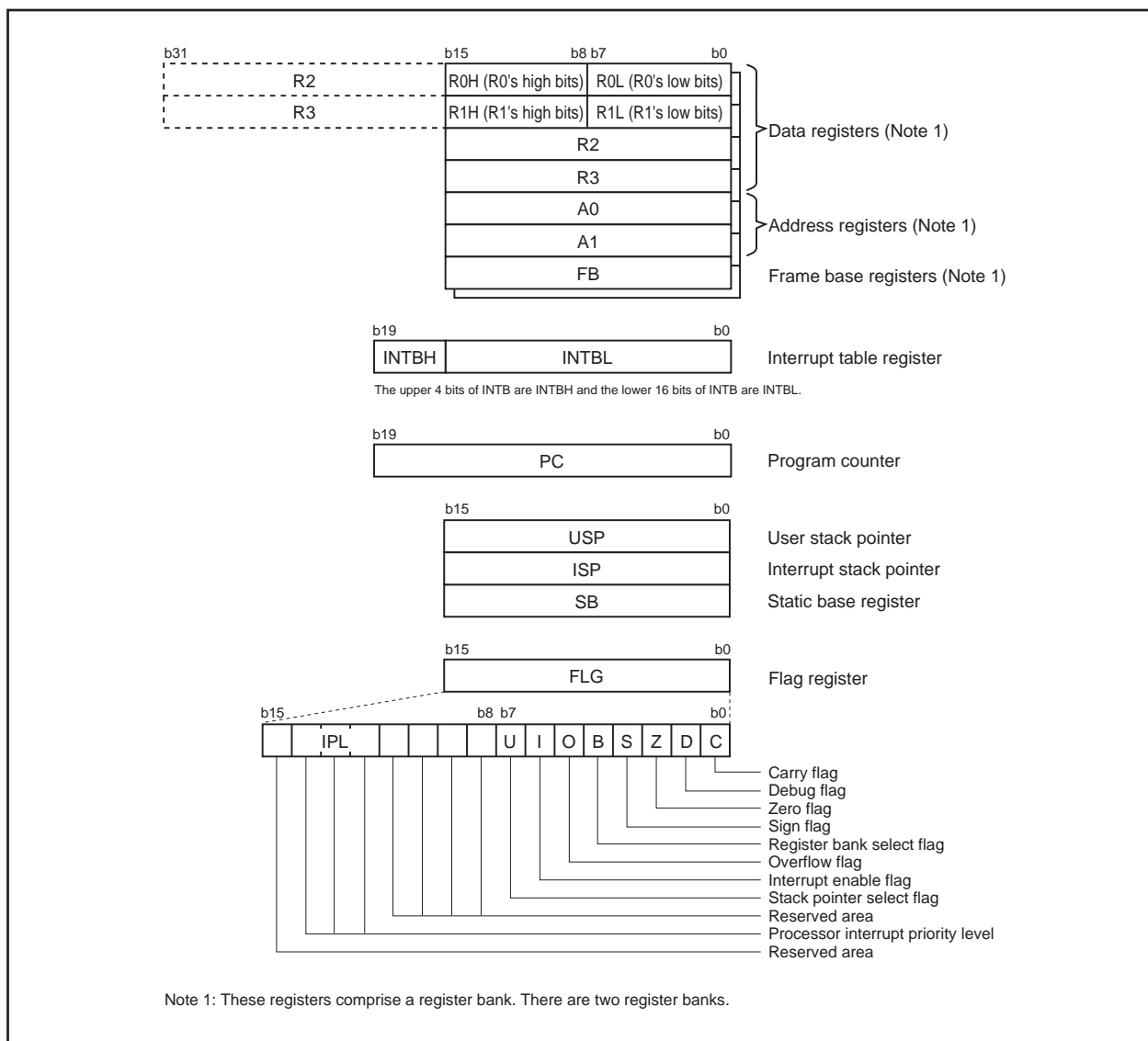


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers. R1H and R1L are the same as R0H and R0L. Conversely R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is the same as R2R0.

2.2 Address Registers (A0 and A1)

The A0 register consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and arithmetic/logic operations. A1 is the same as A0.

In some instructions, A1 and A0 can be combined for use as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

2.6 User Stack Pointer (USP), Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.

Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

2.8.2 Debug Flag (D Flag)

This flag is used exclusively for debugging purpose. During normal use, it must be set to "0".

2.8.3 Zero Flag (Z Flag)

This flag is set to "1" when an arithmetic operation resulted in 0; otherwise, it is "0".

2.8.4 Sign Flag (S Flag)

This flag is set to "1" when an arithmetic operation resulted in a negative value; otherwise, it is "0".

2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is "0"; register bank 1 is selected when this flag is "1".

2.8.6 Overflow Flag (O Flag)

This flag is set to "1" when the operation resulted in an overflow; otherwise, it is "0".

2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.

Maskable interrupts are disabled when the I flag is "0", and are enabled when the I flag is "1". The I flag is set to "0" when the interrupt request is accepted.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is "0"; USP is selected when the U flag is "1".

The U flag is set to "0" when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has priority greater than IPL, the interrupt request is enabled.

2.8.10 Reserved Area

When write to this bit, write "0". When read, its content is indeterminate.

3. Memory

Figure 3.1 is a memory map. The address space extends the 1M bytes from address 00000₁₆ to FFFFF₁₆. From FFFFF₁₆ down is ROM. For example, in the M301N2M4T-XXXFP, there is 32K bytes of internal ROM from F8000₁₆ to FFFFF₁₆. The vector table for fixed interrupts such as the reset are mapped to FFFDC₁₆ to FFFFF₁₆. The starting address of the interrupt routine is stored here. The address of the vector table for timer interrupts, etc., can be set as desired using the internal register (INTB). See the section on interrupts for details.

From 00400₁₆ up is RAM. For example, in the M301N2M4T-XXXFP, there is 1K byte of internal RAM from 00400₁₆ to 007FF₁₆. In addition to storing data, the RAM also stores the stack used when calling subroutines and when interrupts are generated.

The SFR area is mapped to 00000₁₆ to 003FF₁₆. This area accommodates the control registers for peripheral devices such as I/O ports, A/D converter, serial I/O, and timers, etc. Any part of the SFR area that is not occupied is reserved and cannot be used for other purposes.

The special page vector table is mapped to FFE00₁₆ to FFFDB₁₆. If the starting addresses of subroutines or the destination addresses of jumps are stored here, subroutine call instructions and jump instructions can be used as 2-byte instructions, reducing the number of program steps.

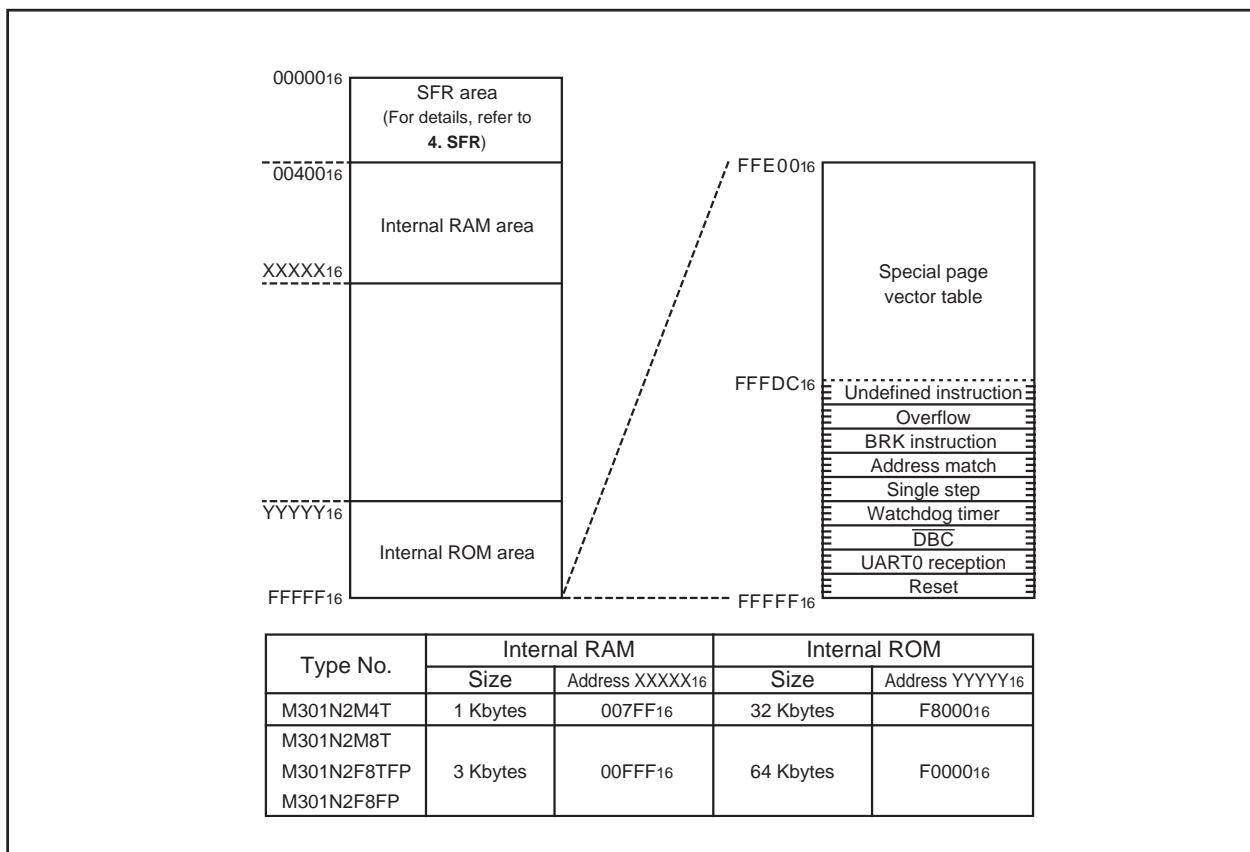


Figure 3.1 Memory map

Address	Register	Symbol	After reset
0040 ₁₆			
0041 ₁₆			
0042 ₁₆			
0043 ₁₆			
0044 ₁₆			
0045 ₁₆	CAN0 wakeup interrupt control register	C01WKIC	XXXXX000 ₂
0046 ₁₆	CAN0 state/error interrupt control register	C01ERRIC	XXXXX000 ₂
0047 ₁₆			
0048 ₁₆	CAN0 reception successful interrupt control register	C0RECIC	XXXXX000 ₂
0049 ₁₆	CAN0 transmission successful interrupt control register	C0TRMIC	XXXXX000 ₂
004A ₁₆			
004B ₁₆			
004C ₁₆			
004D ₁₆	Key input interrupt control register	KUPIC	XXXXX000 ₂
004E ₁₆	A/D conversion interrupt control register	ADIC	XXXXX000 ₂
004F ₁₆			
0050 ₁₆			
0051 ₁₆	UART0 transmit interrupt control register	S0TIC	XXXXX000 ₂
0052 ₁₆	UART0 receive interrupt control register	S0RIC	XXXXX000 ₂
0053 ₁₆	UART1 transmit interrupt control register	S1TIC	XXXXX000 ₂
0054 ₁₆	UART1 receive interrupt control register	S1RIC	XXXXX000 ₂
0055 ₁₆	Timer 1 interrupt control register	T1IC	XXXXX000 ₂
0056 ₁₆	Timer X interrupt control register	TXIC	XXXXX000 ₂
0057 ₁₆	Timer Y interrupt control register	TYIC	XXXXX000 ₂
0058 ₁₆	Timer Z interrupt control register	TZIC	XXXXX000 ₂
0059 ₁₆	CNTR0 interrupt control register	CNTR0IC	XXXXX000 ₂
005A ₁₆	TCIN interrupt control register	TCINIC	XXXXX000 ₂
005B ₁₆	Timer C interrupt control register	TCIC	XXXXX000 ₂
005C ₁₆	INT3 interrupt control register	INT3IC	XXXXX000 ₂
005D ₁₆	INT0 interrupt control register	INT0IC	XX00X000 ₂
005E ₁₆	INT1 interrupt control register	INT1IC	XX00X000 ₂
005F ₁₆	INT2 interrupt control register	INT2IC	XX00X000 ₂
0060 ₁₆			
0061 ₁₆			
0062 ₁₆			
0063 ₁₆			
0064 ₁₆			
0065 ₁₆			
0066 ₁₆			
0067 ₁₆			
0068 ₁₆			
0069 ₁₆			
006A ₁₆			
006B ₁₆			
006C ₁₆			
006D ₁₆			
006E ₁₆			
006F ₁₆			
0070 ₁₆			
0071 ₁₆			
0072 ₁₆			
0073 ₁₆			
0074 ₁₆			
0075 ₁₆			
0076 ₁₆			
0077 ₁₆			
0078 ₁₆			
0079 ₁₆			
007A ₁₆			
007B ₁₆			
007C ₁₆			
007D ₁₆			
007E ₁₆			
007F ₁₆			

Note 1: Location in the SFR area where nothing is allocated are reserved areas. Do not access these areas for read or write.

X : Undefined

Address	Register	Symbol	After reset
00C0 ₁₆	A/D register	AD	XX ₁₆
00C1 ₁₆			XX ₁₆
00C2 ₁₆			
00C3 ₁₆			
00C4 ₁₆			
00C5 ₁₆			
00C6 ₁₆			
00C7 ₁₆			
00C8 ₁₆			
00C9 ₁₆			
00CA ₁₆			
00CB ₁₆			
00CC ₁₆			
00CD ₁₆			
00CE ₁₆			
00CF ₁₆			
00D0 ₁₆			
00D1 ₁₆			
00D2 ₁₆			
00D3 ₁₆			
00D4 ₁₆	A/D control register 2	ADCON2	XXXX0000 ₂
00D5 ₁₆			
00D6 ₁₆	A/D control register 0	ADCON0	00000XXX ₂
00D7 ₁₆	A/D control register 1	ADCON1	00 ₁₆
00D8 ₁₆	D/A register	DA	XX ₁₆
00D9 ₁₆			
00DA ₁₆			
00DB ₁₆			
00DC ₁₆	D/A control register	DACON	XXXXXX0X0 ₂
00DD ₁₆			
00DE ₁₆			
00DF ₁₆			
00E0 ₁₆	Port P0 register	P0	XX ₁₆
00E1 ₁₆	Port P1 register	P1	XX ₁₆
00E2 ₁₆	Port P0 direction register	PD0	00 ₁₆
00E3 ₁₆	Port P1 direction register	PD1	00 ₁₆
00E4 ₁₆	Port P2 register	P2	XX ₁₆
00E5 ₁₆	Port P3 register	P3	XX ₁₆
00E6 ₁₆	Port P2 direction register	PD2	XXXXXXXX00 ₂
00E7 ₁₆	Port P3 direction register	PD3	00 ₁₆
00E8 ₁₆	Port P4 register	P4	XX ₁₆
00E9 ₁₆	Port P5 register	P5	XX ₁₆
00EA ₁₆	Port P4 direction register	PD4	00 ₁₆
00EB ₁₆	Port P5 direction register	PD5	XXXXXX000 ₂
00EC ₁₆			
00ED ₁₆			
00EE ₁₆			
00EF ₁₆			
00F0 ₁₆			
00F1 ₁₆			
00F2 ₁₆			
00F3 ₁₆			
00F4 ₁₆			
00F5 ₁₆			
00F6 ₁₆			
00F7 ₁₆			
00F8 ₁₆	CAN0 I/O port select register	CIOSR	XXXXXXXX0 ₂
00F9 ₁₆			
00FA ₁₆			
00FB ₁₆			
00FC ₁₆	Pull-up control register 0	PUR0	00X00000 ₂
00FD ₁₆	Pull-up control register 1	PUR1	XXXXXXXX000 ₂
00FE ₁₆	Port P1 drive capacity control register	DRR	00 ₁₆
00FF ₁₆			

Note 1: Location in the SFR area where nothing is allocated are reserved areas. Do not access these areas for read or write.

X : Undefined

Address	Register	Symbol	After reset
0100 ₁₆			
0101 ₁₆			
0102 ₁₆			
0103 ₁₆			
0104 ₁₆			
01B0 ₁₆			
01B1 ₁₆			
01B2 ₁₆			
01B3 ₁₆	Flash memory control register 4 (Note 2)	FMR4	01000000 ₂
01B4 ₁₆			
01B5 ₁₆	Flash memory control register 1 (Note 2)	FMR1	0000XX0X ₂
01B6 ₁₆			
01B7 ₁₆	Flash memory control register 0 (Note 2)	FMR0	XX000001 ₂
01B8 ₁₆			
01B9 ₁₆			
01BA ₁₆			
01BB ₁₆			
01BC ₁₆			
01BD ₁₆			
01BE ₁₆			
01BF ₁₆			
0215 ₁₆			
0216 ₁₆			
0217 ₁₆			
0218 ₁₆			
0219 ₁₆			
021A ₁₆			
021B ₁₆			
021C ₁₆			
021D ₁₆			
021E ₁₆			
021F ₁₆			
0220 ₁₆	CAN0 message control register 0	C0MCTL0	00 ₁₆
0221 ₁₆	CAN0 message control register 1	C0MCTL1	00 ₁₆
0222 ₁₆	CAN0 message control register 2	C0MCTL2	00 ₁₆
0223 ₁₆	CAN0 message control register 3	C0MCTL3	00 ₁₆
0224 ₁₆	CAN0 message control register 4	C0MCTL4	00 ₁₆
0225 ₁₆	CAN0 message control register 5	C0MCTL5	00 ₁₆
0226 ₁₆	CAN0 message control register 6	C0MCTL6	00 ₁₆
0227 ₁₆	CAN0 message control register 7	C0MCTL7	00 ₁₆
0228 ₁₆	CAN0 message control register 8	C0MCTL8	00 ₁₆
0229 ₁₆	CAN0 message control register 9	C0MCTL9	00 ₁₆
022A ₁₆	CAN0 message control register 10	C0MCTL10	00 ₁₆
022B ₁₆	CAN0 message control register 11	C0MCTL11	00 ₁₆
022C ₁₆	CAN0 message control register 12	C0MCTL12	00 ₁₆
022D ₁₆	CAN0 message control register 13	C0MCTL13	00 ₁₆
022E ₁₆	CAN0 message control register 14	C0MCTL14	00 ₁₆
022F ₁₆	CAN0 message control register 15	C0MCTL15	00 ₁₆
0230 ₁₆	CAN0 control register	C0CTLR	X0000001 ₂
0231 ₁₆			XX0X0000 ₂
0232 ₁₆	CAN0 status register	C0STR	00 ₁₆
0233 ₁₆			X0000001 ₂
0234 ₁₆	CAN0 slot status register	C0SSTR	0000 ₁₆
0235 ₁₆			0000 ₁₆
0236 ₁₆	CAN0 interrupt control register	C0ICR	0000 ₁₆
0237 ₁₆			0000 ₁₆
0238 ₁₆	CAN0 extended ID register	C0IDR	0000 ₁₆
0239 ₁₆			0000 ₁₆
023A ₁₆	CAN0 configuration register	C0CONR	XX ₁₆
023B ₁₆			XX ₁₆
023C ₁₆	CAN0 receive error count register	C0RECR	00 ₁₆
023D ₁₆	CAN0 transmit error count register	C0TECR	00 ₁₆
023E ₁₆			
023F ₁₆			

Note 1: Location in the SFR area where nothing is allocated are reserved areas. Do not access these areas for read or write.

Note 2: These registers are available on flash memory versions only.

X : Undefined

Address	Register	Symbol	After reset
02C0 ₁₆	CAN0 slot 6: Identifier / DLC		XX ₁₆
02C1 ₁₆			XX ₁₆
02C2 ₁₆			XX ₁₆
02C3 ₁₆			XX ₁₆
02C4 ₁₆			XX ₁₆
02C5 ₁₆			XX ₁₆
02C6 ₁₆	CAN0 slot 6: Data Field		XX ₁₆
02C7 ₁₆			XX ₁₆
02C8 ₁₆			XX ₁₆
02C9 ₁₆			XX ₁₆
02CA ₁₆			XX ₁₆
02CB ₁₆			XX ₁₆
02CC ₁₆			XX ₁₆
02CD ₁₆			XX ₁₆
02CE ₁₆	CAN0 slot 6: Time Stamp		XX ₁₆
02CF ₁₆			XX ₁₆
02D0 ₁₆	CAN0 slot 7: Identifier / DLC		XX ₁₆
02D1 ₁₆			XX ₁₆
02D2 ₁₆			XX ₁₆
02D3 ₁₆			XX ₁₆
02D4 ₁₆			XX ₁₆
02D5 ₁₆			XX ₁₆
02D6 ₁₆	CAN0 slot 7: Data Field		XX ₁₆
02D7 ₁₆			XX ₁₆
02D8 ₁₆			XX ₁₆
02D9 ₁₆			XX ₁₆
02DA ₁₆			XX ₁₆
02DB ₁₆			XX ₁₆
02DC ₁₆			XX ₁₆
02DD ₁₆			XX ₁₆
02DE ₁₆	CAN0 slot 7: Time Stamp		XX ₁₆
02DF ₁₆			XX ₁₆
02E0 ₁₆	CAN0 slot 8: Identifier / DLC		XX ₁₆
02E1 ₁₆			XX ₁₆
02E2 ₁₆			XX ₁₆
02E3 ₁₆			XX ₁₆
02E4 ₁₆			XX ₁₆
02E5 ₁₆			XX ₁₆
02E6 ₁₆	CAN0 slot 8: Data Field		XX ₁₆
02E7 ₁₆			XX ₁₆
02E8 ₁₆			XX ₁₆
02E9 ₁₆			XX ₁₆
02EA ₁₆			XX ₁₆
02EB ₁₆			XX ₁₆
02EC ₁₆			XX ₁₆
02ED ₁₆			XX ₁₆
02EE ₁₆	CAN0 slot 8: Time Stamp		XX ₁₆
02EF ₁₆			XX ₁₆
02F0 ₁₆	CAN0 slot 9: Identifier / DLC		XX ₁₆
02F1 ₁₆			XX ₁₆
02F2 ₁₆			XX ₁₆
02F3 ₁₆			XX ₁₆
02F4 ₁₆			XX ₁₆
02F5 ₁₆			XX ₁₆
02F6 ₁₆	CAN0 slot 9: Data Field		XX ₁₆
02F7 ₁₆			XX ₁₆
02F8 ₁₆			XX ₁₆
02F9 ₁₆			XX ₁₆
02FA ₁₆			XX ₁₆
02FB ₁₆			XX ₁₆
02FC ₁₆			XX ₁₆
02FD ₁₆			XX ₁₆
02FE ₁₆	CAN0 slot 9: Time Stamp		XX ₁₆
02FF ₁₆			XX ₁₆

Note 1: Location in the SFR area where nothing is allocated are reserved areas. Do not access these areas for read or write.

X : Undefined

Address	Register	Symbol	After reset
0300 ₁₆	CAN0 slot 10: Identifier / DLC		XX ₁₆
0301 ₁₆			XX ₁₆
0302 ₁₆			XX ₁₆
0303 ₁₆			XX ₁₆
0304 ₁₆			XX ₁₆
0305 ₁₆			XX ₁₆
0306 ₁₆	CAN0 slot 10: Data Field		XX ₁₆
0307 ₁₆			XX ₁₆
0308 ₁₆			XX ₁₆
0309 ₁₆			XX ₁₆
030A ₁₆			XX ₁₆
030B ₁₆			XX ₁₆
030C ₁₆	CAN0 slot 10: Time Stamp		XX ₁₆
030D ₁₆			XX ₁₆
030E ₁₆	CAN0 slot 11: Identifier / DLC		XX ₁₆
030F ₁₆			XX ₁₆
0310 ₁₆			XX ₁₆
0311 ₁₆			XX ₁₆
0312 ₁₆			XX ₁₆
0313 ₁₆			XX ₁₆
0314 ₁₆	CAN0 slot 11: Data Field		XX ₁₆
0315 ₁₆			XX ₁₆
0316 ₁₆			XX ₁₆
0317 ₁₆			XX ₁₆
0318 ₁₆			XX ₁₆
0319 ₁₆			XX ₁₆
031A ₁₆	CAN0 slot 11: Time Stamp		XX ₁₆
031B ₁₆			XX ₁₆
031C ₁₆	CAN0 slot 12: Identifier / DLC		XX ₁₆
031D ₁₆			XX ₁₆
031E ₁₆			XX ₁₆
031F ₁₆			XX ₁₆
0320 ₁₆			XX ₁₆
0321 ₁₆			XX ₁₆
0322 ₁₆	CAN0 slot 12: Data Field		XX ₁₆
0323 ₁₆			XX ₁₆
0324 ₁₆			XX ₁₆
0325 ₁₆			XX ₁₆
0326 ₁₆			XX ₁₆
0327 ₁₆			XX ₁₆
0328 ₁₆	CAN0 slot 12: Time Stamp		XX ₁₆
0329 ₁₆			XX ₁₆
032A ₁₆			XX ₁₆
032B ₁₆			XX ₁₆
032C ₁₆			XX ₁₆
032D ₁₆			XX ₁₆
032E ₁₆	CAN0 slot 13: Identifier / DLC		XX ₁₆
032F ₁₆			XX ₁₆
0330 ₁₆			XX ₁₆
0331 ₁₆			XX ₁₆
0332 ₁₆			XX ₁₆
0333 ₁₆			XX ₁₆
0334 ₁₆	CAN0 slot 13: Data Field		XX ₁₆
0335 ₁₆			XX ₁₆
0336 ₁₆			XX ₁₆
0337 ₁₆			XX ₁₆
0338 ₁₆			XX ₁₆
0339 ₁₆			XX ₁₆
033A ₁₆	CAN0 slot 13: Time Stamp		XX ₁₆
033B ₁₆			XX ₁₆
033C ₁₆			XX ₁₆
033D ₁₆			XX ₁₆
033E ₁₆			XX ₁₆
033F ₁₆			XX ₁₆

Note 1: Location in the SFR area where nothing is allocated are reserved areas. Do not access these areas for read or write.

X : Undefined

5. Electrical Characteristics

Table 5.1 Absolute maximum ratings

Symbol	Parameter		Condition	Rated value	Unit
V _{cc}	Supply voltage			- 0.3 to 6.5	V
V _i	Input voltage	RESET, V _{REF} , X _{IN} P0 ₀ to P0 ₇ , P1 ₀ to P1 ₇ , P2 ₀ , P2 ₁ , P3 ₀ to P3 ₇ , P4 ₀ to P4 ₇ , P5 ₀ to P5 ₂ , CNVss (Note 1)		- 0.3 to V _{cc} + 0.3	V
V _o	Output voltage	P0 ₀ to P0 ₇ , P1 ₀ to P1 ₇ , P2 ₀ , P2 ₁ , P3 ₀ to P3 ₇ , P4 ₀ to P4 ₇ , P5 ₀ to P5 ₂ , X _{OUT}		- 0.3 to V _{cc} + 0.3	V
		I _{Vcc}		- 0.3 to 2.8V	V
P _d	Power dissipation		T _{opr} = 25 °C	300	mW
T _{opr}	Operating ambient temperature			- 40 to 85 (Note 2)	°C
T _{stg}	Storage temperature			- 65 to 150	°C

Note 1: CNVss pin of flash memory version: -0.3 to 6.5 V

Note 2: When flash memory version is program/erase mode: 0 to 60 °C

Table 5.2 Recommended operating conditions
(Unless otherwise noted: V_{CC} = 4.2V to 5.5V, T_{opr} = -40 to 85°C)

Symbol	Parameter		Standard			Unit
			Min	Typ.	Max.	
V _{CC}	Supply voltage		4.2	5.0	5.5	V
V _{SS}	Supply voltage			0		V
V _{IH}	HIGH input voltage	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52, X _{IN} , RESET, CNV _{SS}	0.8V _{CC}		V _{CC}	V
V _{IL}	LOW input voltage	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52, X _{IN} , RESET, CNV _{SS}	0		0.2V _{CC}	V
I _{OH} (peak)	HIGH peak output current	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52			- 10.0	mA
I _{OH} (avg)	HIGH average output current	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52			- 5.0	mA
I _{OL} (peak)	LOW peak output current	P00 to P07, P20, P21, P30 to P37, P40 to P47, P50 to P52			10.0	mA
		P10 to P17	HIGH POWER		20.0	mA
			LOW POWER		10.0	
I _{OL} (avg)	LOW average output current	P00 to P07, P20, P21, P30 to P37, P40 to P47, P50 to P52			5.0	mA
		P10 to P17	HIGH POWER		10.0	mA
			LOW POWER		5.0	
f (X _{IN})	Main clock input oscillation frequency (Note 3)		V _{CC} =4.2V to 5.5V	0	16	MHz
f (X _{CIN})	Subclock oscillation frequency			32.768	50	kHz

Note 1: The average output current is an average value measured over 100ms.

Note 2: Keep output current as follows:

The sum of port P00 to P03, P13 to P17, P21, P34 to P37, P46, P47, P50 to P52 I_{OL} (peak) is under 60 mA. The sum of port P00 to P03, P13 to P17, P21, P34 to P37, P46, P47, P50 to P52 I_{OH} (peak) is under 60 mA. The sum of port P04 to P07, P10 to P12, P20, P30 to P33, P40 to P45 I_{OL} (peak) is under 60 mA. The sum of port P04 to P07, P10 to P12, P20, P30 to P33, P40 to P45 I_{OH} (peak) is under 60 mA.

Note 3: Relationship between main clock oscillation frequency and supply voltage is shown as below.

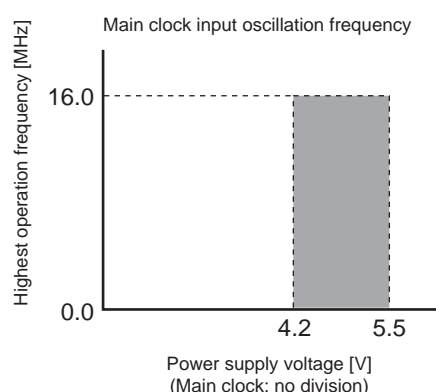


Table 5.3 Electrical characteristics (1)**(Unless otherwise noted: VCC = 5V, VSS = 0V at Topr = -40 to 85°C, f(XIN) = 16MHz)**

Symbol	Parameter		Measuring condition	Standard			Unit
				Min.	Typ.	Max.	
VOH	HIGH output voltage	P00 to P07, P10 to P17, P20 to P21, P30 to P37, P40 to P47, P50 to P52	IOH = - 5 mA	3.0			V
			IOH = - 200 µA	4.7			
VOH	HIGH output voltage	XOUT	HIGH POWER	3.0			V
			LOW POWER	3.0			
VOH	HIGH output voltage	XCOUT	HIGH POWER		2.5		V
			LOW POWER		1.6		
VOL	LOW output voltage	P00 to P07, P20, P21, P30 to P37, P40 to P47, P50 to P52	IOL = 5 mA			2.0	V
			IOL = 200 µA			0.45	
VOL	LOW output voltage	P10 to P17	HIGH POWER			2.0	V
			LOW POWER			2.0	
VOL	LOW output voltage	XOUT	HIGH POWER			2.0	V
			LOW POWER			2.0	
VOL	LOW output voltage	XCOUT	HIGH POWER		0		V
			LOW POWER		0		
VT+ -VT-	Hysteresis	CNTR0, TCIN, INT0 to INT3, CLK0, CLK1, P45 Rx D0, Rx D1, KI0 to KI3, CRX0		0.2		0.8	V
VT+ -VT-	Hysteresis	RESET		0.2		1.8	V
IiH	HIGH input current	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52, XIN, RESET, CNVSS	VI = 5V			5.0	µA
IiL	LOW input current	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52, XIN, RESET, CNVSS	VI = 0V			-5.0	µA
RPULLUP	Pull-up resistor	P00 to P07, P10 to P17, P20, P21, P30 to P37, P40 to P47, P50 to P52	VI = 0V	30.0	50.0	167.0	kΩ
RfxIN	Feedback resistor	XIN			1.0		MΩ
RfxCIN	Feedback resistor	XCIN			15.0		MΩ
VRAM	RAM retention voltage		When clock is stopped	2.0			V
ROSC	Oscillation frequency of On-chip oscillator	Mask ROM		300	600	1200	kHz
		Flash memory					

Table 5.4 Electrical characteristics (2)**(Unless otherwise noted: $V_{CC} = 5V$, $V_{SS} = 0V$ at $T_{opr} = 25^{\circ}C$, $f(X_{IN}) = 16MHz$)**

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
I _{cc}	Power supply current	I/O pin has no load Mask ROM		12.0	22.0	mA
				14.0	24.0	
		Flash memory				mA
		Mask ROM		300		μA
		Flash memory		800		μA
		Mask ROM		60		μA
		Flash memory		100		μA

Table 5.5 Power supply timing circuit characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Timer for internal power supply stabilization during powering-on	$V_{CC} = 4.2$ to 5.5 V			2	ms
td(R-S)	Stop release time				150	μs
td(W-S)	Wait release time during low power dissipation mode				150	μs
td(M-L)	Timer for internal power supply stabilization when main clock oscillation starts				150	μs

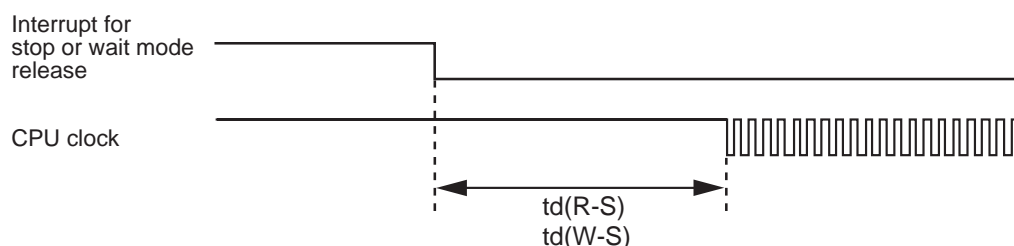


Table 5.6 Flash memory version electrical characteristics
(Unless otherwise noted: Vcc = 4.2 to 5.5 V, Topr = 0 to 60°C)

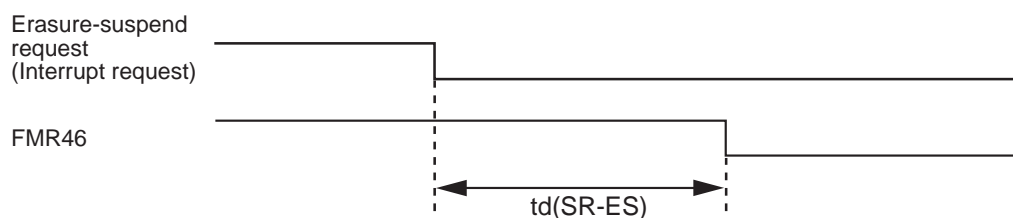
Symbol	Parameter	Standard			Unit
		Min.	Typ. (Note 1)	Max.	
-	Erase/write cycle (Note 2)	100 (Note 3)			cycle
-	Word programming time		75	600	μs
-	Block erasing time	2Kbyte block	0.2	9	s
		8Kbyte block	0.4	9	s
		16Kbyte block	0.7	9	s
		32Kbyte block	1.2	9	s
td(SR-ES)	Transition time from erasure operation to erase-suspend			20	ms
-	Data retention	10			year

Note1: Vcc=5.0V, Topr=25°C

Note2: Definition of Programming and erasure times

The Programming and erasure times are defined to be per-block erasure times. For example a case where a 2K-byte block is programmed in 1,024 operations by writing one word at a time and erased thereafter. Performing multiple programs to the same address before an erase operation is prohibited.

Note 3: Minimum number of programming/erasure for which operation is guaranteed.



5.1 Timing requirements

(Unless otherwise noted: $V_{CC} = 5V$, $V_{SS} = 0V$ at $T_{opr} = -40$ to $85^{\circ}C$)

Table 5.9 XIN input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	62.5		ns
$t_{wH(XIN)}$	XIN input HIGH pulse width	30		ns
$t_{wL(XIN)}$	XIN input LOW pulse width	30		ns

Table 5.10 CNTR0 input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CNTR0)}$	CNTR0 input cycle time	100		ns
$t_{wH(CNTR0)}$	CNTR0 input HIGH pulse width	40		ns
$t_{wL(CNTR0)}$	CNTR0 input LOW pulse width	40		ns

Table 5.11 TCIN input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TCIN)}$	TCIN input cycle time	400(Note 1)		ns
$t_{wH(TCIN)}$	TCIN input HIGH pulse width	200(Note 2)		ns
$t_{wL(TCIN)}$	TCIN input LOW pulse width	200(Note 2)		ns

Note 1: Use the greater value, either (1/digital filter clock frequency X 6) or min. value.

Note 2: Use the greater value, either (1/digital filter clock frequency X 3) or min. value.

Table 5.12 Serial I/O

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CLK)}$	CLKi input cycle time	200		ns
$t_{w(CLKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CLKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TxDi output delay time		80	ns
$t_{h(C-Q)}$	TxDi hold time	0		ns
$t_{su(D-C)}$	RxDi input setup time	30		ns
$t_{h(C-D)}$	RxDi input hold time	90		ns

Table 5.13 External interrupt \overline{INTi} input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	\overline{INTi} input HIGH pulse width	250(Note 1)		ns
$t_{w(INL)}$	\overline{INTi} input LOW pulse width	250(Note 2)		ns

Note 1: When the $\overline{INT0}$ input filter select bit selects the digital filter, use the $\overline{INT0}$ input HIGH pulse width to the greater value, either (1/digital filter clock frequency X 3) or min. value.

Note 2: When the $\overline{INT0}$ input filter select bit selects the digital filter, use the $\overline{INT0}$ input LOW pulse width to the greater value, either (1/digital filter clock frequency X 3) or min. value.

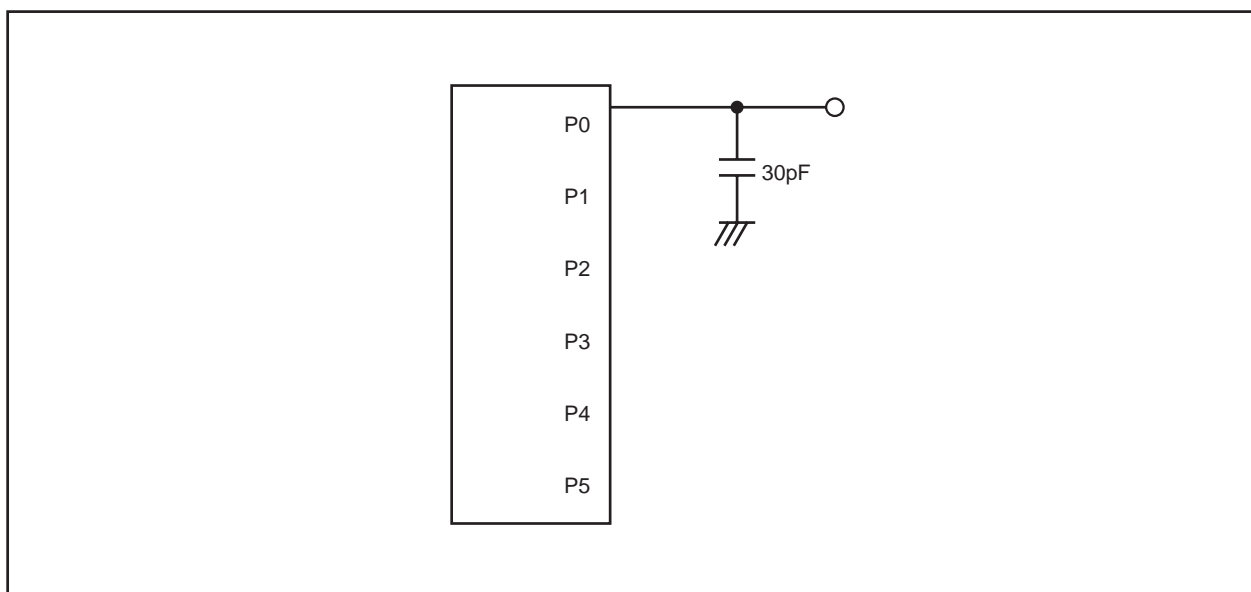


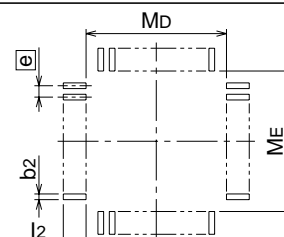
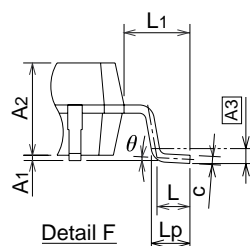
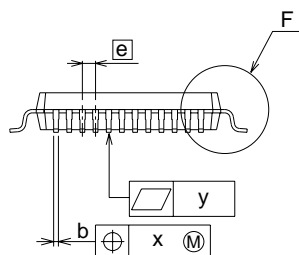
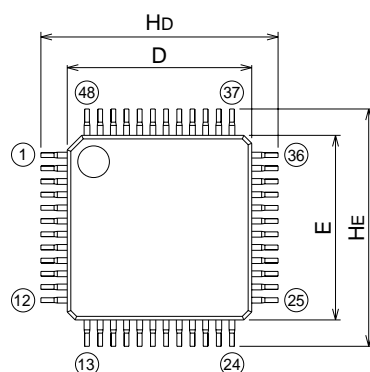
Figure 5.1 Port P0 to P5 measurement circuit

Package Dimension

48P6Q-A Recommended

Plastic 48pin 7X7mm body LQFP

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
LQFP48-P-77-0.50	—	—	Cu Alloy



Recommended Mount Pad

Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	1.7
A1	0	0.1	0.2
A2	—	1.4	—
b	0.17	0.22	0.27
c	0.105	0.125	0.175
D	6.9	7.0	7.1
E	6.9	7.0	7.1
e	—	0.5	—
Hd	8.8	9.0	9.2
HE	8.8	9.0	9.2
L	0.35	0.5	0.65
L1	—	1.0	—
Lp	0.45	0.6	0.75
A3	—	0.25	—
x	—	—	0.08
y	—	—	0.1
θ	0°	—	8°
b2	—	0.225	—
l2	1.0	—	—
Md	—	7.4	—
ME	—	7.4	—

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Tel: <65> 6213-0200, Fax: <65> 6278-8001